

TC74HC221AP, TC74HC221AF, TC74HC221AFN

DUAL MONOSTABLE MULTIVIBRATOR

The TC74HC221A is a high speed CMOS MONOSTABLE MULTIVIBRATOR fabricated with silicon gate C²MOS technology.

It achieves the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

There are two trigger inputs, $\overline{A}$ input (Negative edge), and B input (Positive edge). These inputs are valid for a slow rise/fall time signal ($t_r = t_f = 1\text{sec.}$) as they are schmitt trigger inputs. This device may also be triggered by using $\overline{\text{CLR}}$ input (Positive edge).

After triggering, the output stays in a MONOSTABLE state for a time period determined by the external resistor and capacitor (R_x, C_x). A low level at the $\overline{\text{CLR}}$ input breaks this state.

Limits for C_x and R_x are:

External capacitor, C_x No limit

External resistor, R_x $V_{CC} = 2.0\text{V}$ more than $5\text{k}\Omega$
 $V_{CC} \geq 3.0\text{V}$ more than $1\text{k}\Omega$

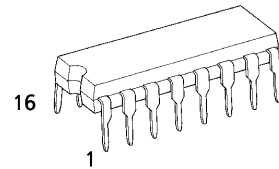
All inputs are equipped with protection circuits against static discharge or transient excess voltage.

FEATURES:

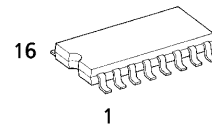
- High Speed..... $t_{pd} = 25\text{ns}$ (typ.) at $V_{CC} = 5\text{V}$
- Low Power Dissipation
 - Standby by State $I_{CC} = 4\mu\text{A}$ (Max.) at $T_a = 25^\circ\text{C}$
 - Active State $I_{CC} = 700\mu\text{A}$ (Max.) at $T_a = 25^\circ\text{C}$
- High Noise Immunity..... $V_{NIH} = V_{NIL} = 28\% V_{CC}$ (Min.)
- Output Drive Capability..... 10 LSTTL Loads
- Symmetrical Output Impedance... $|I_{OH}| = I_{OL} = 4\text{mA}$ (Min.)
- Balanced Propagation Delays..... $t_{PLH} \approx t_{PHL}$
- Wide Operating Voltage Range... V_{CC} (opr.) = $2\text{V} \sim 6\text{V}$
- Pin and Function Compatible with 74LS221

Note: In the case of using only one circuit, $\overline{\text{CLR}}$ should be tied to GND, $R_x / C_x \cdot C_x \cdot Q \cdot \overline{Q}$ should be tied to OPEN, the other inputs should be tied to V_{CC} or GND.

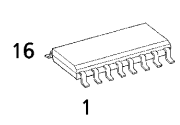
(Note) The JEDEC SOP (FN) is not available in Japan.



P (DIP16-P-300-2.54A)
Weight : 1.00g (Typ.)

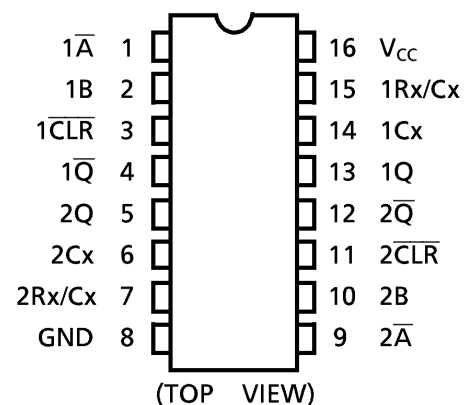


F (SOP16-P-300-1.27)
Weight : 0.18g (Typ.)

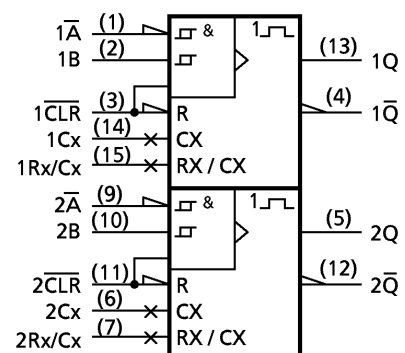


FN (SOL16-P-150-1.27)
Weight : 0.13g (Typ.)

PIN ASSIGNMENT



IEC LOGIC SYMBOL

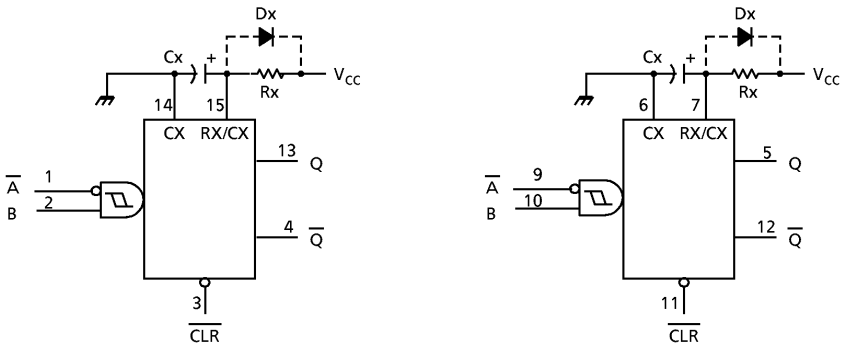


TRUTH TABLE

INPUTS			OUTPUTS		FUNCTION
A	B	CLR	Q	Q	
	H	H			OUTPUT ENABLE
X	L	H	L	H	INHIBIT
H	X	H	L	H	INHIBIT
L		H			OUTPUT ENABLE
L	H				OUTPUT ENABLE
X	X	L	L	H	INHIBIT

X : Don't Care

BLOCK DIAGRAM



Notes : (1) Cx, Rx, Dx are external
Capacitor, Resistor, and Diode, respectively.

(2) External clamping diode, Dx ;

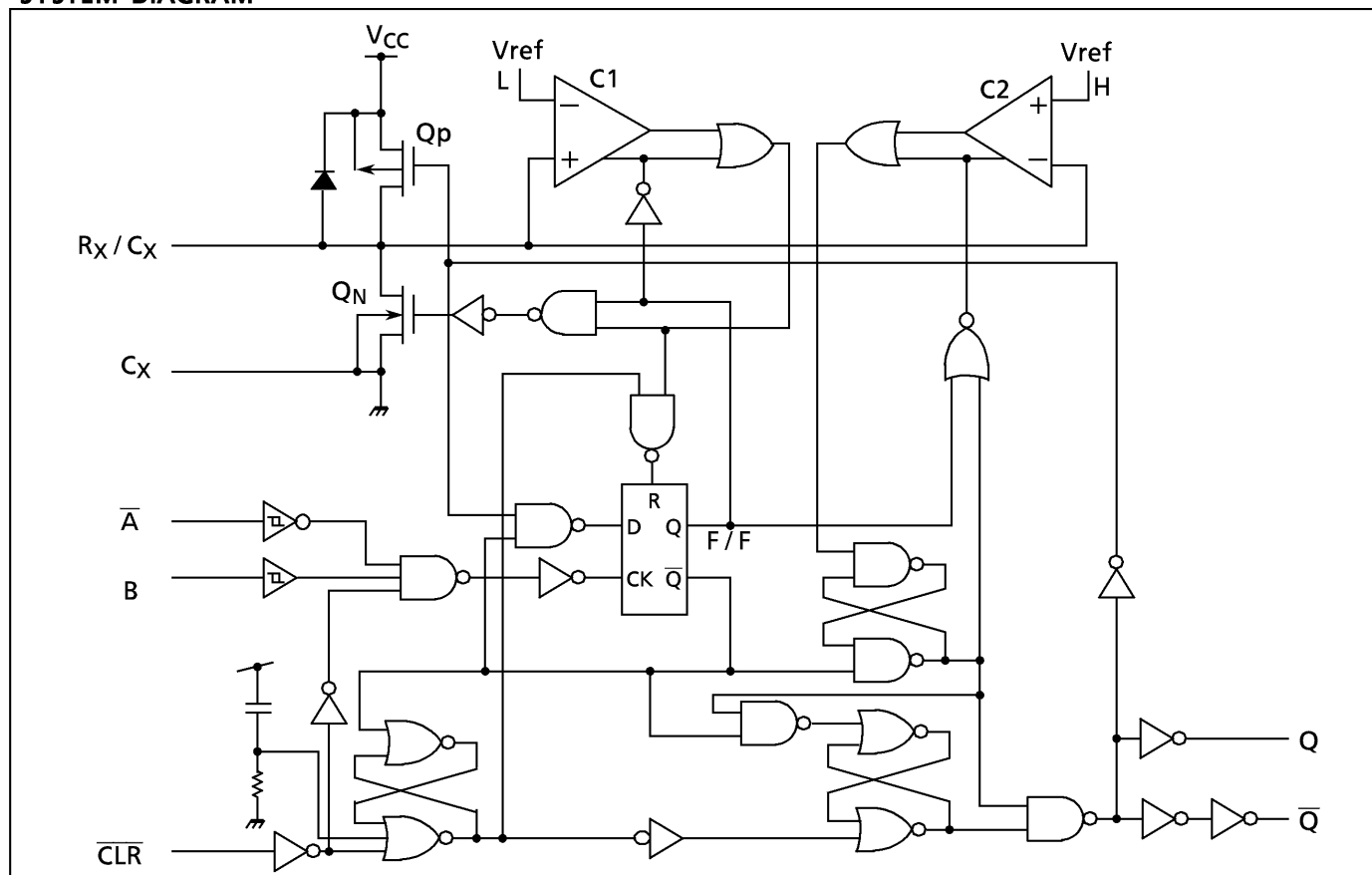
The external capacitor is charged to V_{CC} level in the wait state, i.e. when no trigger is applied.
If the supply voltage is turned off, Cx is discharges mainly through the internal (parasitic) diode. If Cx is sufficiently large and V_{CC} drops rapidly, there will be some possibility of damaging the IC through in rush current or latch-up. If the capacitance of the supply voltage filter is large enough and V_{CC} drops slowly, the in rush current is automatically limited and damage to the IC is avoided.
The maximum value of forward current through the parasitic diode is ±20mA.
In the case of a large Cx, the limit of fall time of the supply voltage is determined as follows:

$$t_f \geq (V_{CC} - 0.7) C_x / 20\text{mA}$$

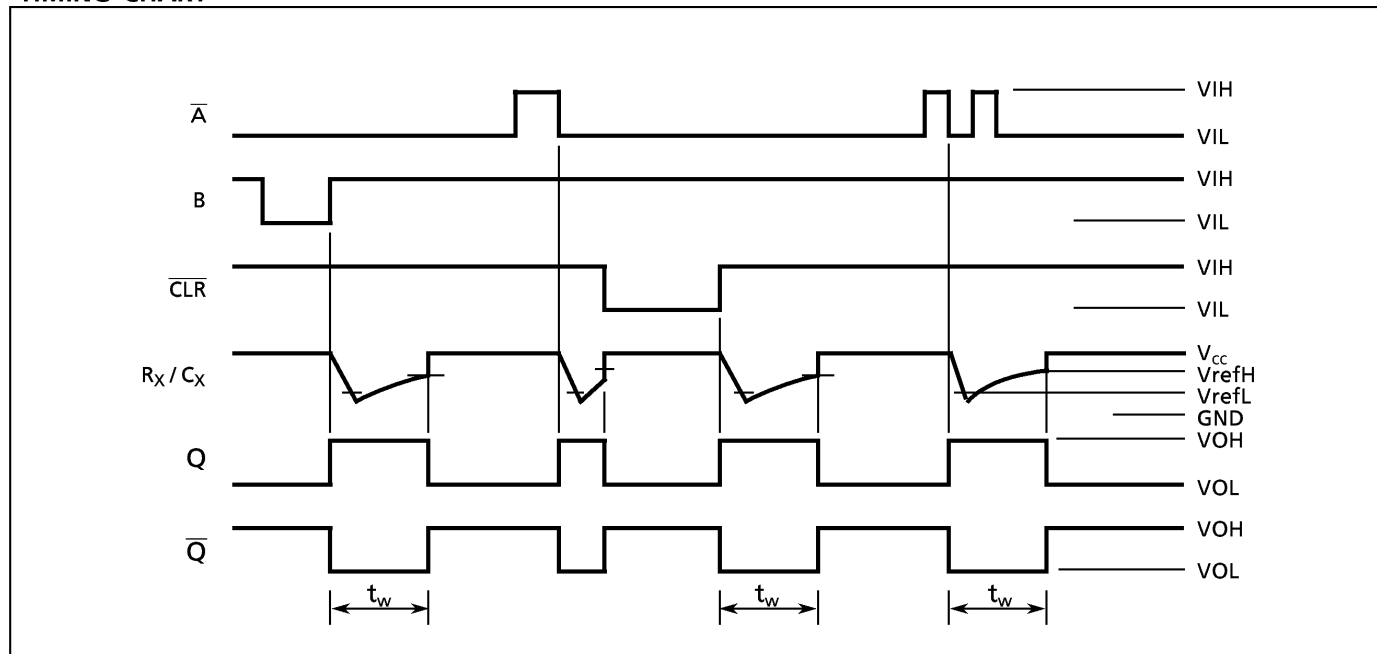
(tf is the time between the supply voltage turn off
and the supply voltage reaching 0.4 V_{CC}.)

In the even a system does not satisfy the above condition, an external clamping diode (Dx) is needed to protect the IC from rush current.

SYSTEM DIAGRAM



TIMING CHART



FUNCTIONAL DESCRIPTION

(1)Stand-by State

The external capacitor (Cx) is fully charged to V_{CC} in the stand-by state. That means, before triggering, the Q_P and Q_N transistors which are connected to the Rx / Cx node are in the off state. Two comparators that relate to the timing of the output pulse, and two reference voltage supplies turn off. The total supply current is only leakage current.

(2)Trigger operation

Trigger operation is effective in any of the following three cases. First the condition where the $\overline{A}$ input is low, and the B input has a rising signal; second, where the B input is high, and the $\overline{A}$ input has a falling signal; and third, where the $\overline{A}$ input is low and the B input is high, and the $\overline{CLR}$ input has a rising signal.

After a trigger becomes effective, comparators C1 and C2 start operating, and Q_N is turned on. The external capacitor discharges through Q_N . The voltage level at the Rx/Cx node drops. If the Rx/Cx voltage level falls to the internal reference voltage V_{refL} , the output of C1 becomes low. The flip-flop is then reset and Q_N turns off. At that moment C1 stops but C2 continues operating.

After Q_N turns off, the voltage at the Rx/Cx node starts rising at a rate determined by the time constant of external capacitor Cx and resistor Rx.

Upon the triggering, output Q becomes high, following some delay time of the internal F/F and gates. It stays high even if the voltage of Rx/Cx changes from falling to rising. When Rx/Cx reaches the internal reference voltage V_{refH} , the output of C2 becomes low, the output Q goes low and C2 stops its operation. That means, after triggering, when the voltage level of the Rx/Cx node reaches V_{refH} , the IC returns to its MONOSTABLE state.

With large values of Cx and Rx, and ignoring the discharge time of the capacitor and internal delays of the IC, the width of the output pulse, t_w (OUT), is as follows:

$$t_w(\text{OUT}) = 1.0 C_x R_x$$

(3)Reset operation

In normal operation, $\overline{CLR}$ input is held high. If $\overline{CLR}$ is low, a trigger has no effect because the Q output is held low and trigger control F/F is reset. Also, Q_P turns on and Cx is charge rapidly to V_{CC} .

This means if $\overline{CLR}$ input is set low, the IC goes into a wait state.

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	$-0.5 \sim 7$	V
DC Input Voltage	V_{IN}	$-0.5 \sim V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	$-0.5 \sim V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 20	mA
DC Output Current	I_{OUT}	± 25	mA
DC V_{CC} / Ground Current	I_{CC}	± 50	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	T_{stg}	$-65 \sim 150$	°C

*500mW in the range of $T_a = -40^\circ\text{C} \sim 65^\circ\text{C}$. From $T_a = 65^\circ\text{C}$ to 85°C a derating factor of $-10\text{mW}/^\circ\text{C}$ shall be applied until 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	$2 \sim 6$	V
Input Voltage	V_{IN}	$0 \sim V_{CC}$	V
Output Voltage	V_{OUT}	$0 \sim V_{CC}$	V
Operating Temperature	T_{opr}	$-40 \sim 85$	°C
Input Rise and Fall Time (CLR Only)	t_r, t_f	$0 \sim 1000 (V_{CC} = 2.0\text{V})$ $0 \sim 500 (V_{CC} = 4.5\text{V})$ $0 \sim 400 (V_{CC} = 6.0\text{V})$	ns
External Capacitor	C_x	No Limitation *	F
External Resistor	R_x	$\geq 5\text{K} * (V_{CC} = 2.0\text{V})$ $\geq 1\text{K} * (V_{CC} \geq 3.0\text{V})$	Ω

* The maximum allowable values of C_x and R_x are a function of leakage of capacitor C_x , the leakage of TC74HC221A, and leakage due to board layout and surface resistance.

Susceptibility to externally induced noise signals may occur for $R_x > 1\text{M}\Omega$.

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION		V_{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT
					MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	V_{IH}			2.0 4.5 6.0	1.50 3.15 4.20	— — —	— — —	1.50 3.15 4.20	— — —	V
Low - Level Input Voltage	V_{IL}			2.0 4.5 6.0	— — —	— — —	0.50 1.35 1.80	— — —	0.50 1.35 1.80	V
High - Level Output Voltage (Q, $\bar{Q}$)	V_{OH}	$V_{IN} =$ V_{IH} or V_{IL}	$I_{OH} = -20\mu A$	2.0 4.5 6.0	1.9 4.4 5.9	2.0 4.5 6.0	— — —	1.9 4.4 5.9	— — —	V
			$I_{OH} = -4\text{ mA}$ $I_{OH} = -5.2\text{ mA}$	4.5 6.0	4.18 5.68	4.31 5.80	— —	4.13 5.63	— —	
Low - Level Output Voltage (Q, $\bar{Q}$)	V_{OL}	$V_{IN} =$ V_{IH} or V_{IL}	$I_{OL} = 20\mu A$	2.0 4.5 6.0	— — —	0.0 0.0 0.0	0.1 0.1 0.1	— — —	0.1 0.1 0.1	V
			$I_{OL} = 4\text{ mA}$ $I_{OL} = 5.2\text{ mA}$	4.5 6.0	— —	0.17 0.18	0.26 0.26	— —	0.33 0.33	
Input Leakage Current	I_{IN}	$V_{IN} = V_{CC}$ or GND		6.0	—	—	± 0.1	—	± 1.0	μA
Rx / Cx Terminal Off - State Current	I_{IN}	$V_{IN} = V_{CC}$ or GND		6.0	—	—	± 0.1	—	± 1.0	
Quiescent Supply Current	I_{CC}	$V_{IN} = V_{CC}$ or GND		6.0	—	—	4.0	—	40.0	
Active - State * Supply Current	I_{CC}	$V_{IN} = V_{CC}$ or GND Rx / Cx = 0.5 V_{CC}		2.0	—	45	200	—	260	μA
				4.5	—	400	500	—	650	μA
				6.0	—	0.7	1.0	—	1.3	mA

*: per circuit

TIMING REQUIREMENTS (Input $t_r = t_f = 6\text{ ns}$)

PARAMETER	SYMBOL	TEST CONDITION	V_{CC} (V)	Ta = 25°C		Ta = -40~85°C	UNIT
				TYP.	LIMIT	LIMIT	
Minimum Pulse Width	$t_{W(L)}$ $t_{W(H)}$		2.0	—	75	95	ns
			4.5	—	15	19	
			6.0	—	13	16	
Minimum Clear Width	$t_{W(L)}$		2.0	—	75	95	
			4.5	—	15	19	
			6.0	—	13	16	

AC ELECTRICAL CHARACTERISTICS ($C_L = 15\text{pF}$, $V_{CC} = 5\text{V}$, $T_a = 25^\circ\text{C}$, Input $t_r = t_f = 6\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Output Transition Time	t_{TLH} t_{THL}		—	4	8	ns
Propagation Delay Time ($\overline{A}$, B—Q, $\overline{Q}$)	t_{PLH} t_{PHL}		—	25	36	
Propagation Delay Time (CLR TRIGGER—Q, $\overline{Q}$)	t_{PLH} t_{PHL}		—	25	41	
Propagation Delay Time ($\overline{\text{CLR}}$ —Q, $\overline{Q}$)	t_{PLH} t_{PHL}		—	16	27	

AC ELECTRICAL CHARACTERISTICS ($C_L = 50\text{pF}$, Input $t_r = t_f = 6\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	V _{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT	
				MIN.	TYP.	MAX.	MIN.	MAX.		
Output Transition Time	t _{TLH} t _{THL}		2.0	—	30	75	—	95	ns	
			4.5	—	8	15	—	19		
			6.0	—	7	13	—	16		
Propagation Delay Time ($\overline{A}$, B—Q, $\overline{Q}$)	t _{pLH} t _{pHL}		2.0	—	102	210	—	265		
			4.5	—	30	42	—	53		
			6.0	—	24	36	—	45		
Propagation Delay Time (CLR TRIGGER—Q, $\overline{Q}$)	t _{pLH} t _{pHL}		2.0	—	102	235	—	295		
			4.5	—	30	47	—	59		
			6.0	—	24	40	—	50		
Propagation Delay Time (CLR—Q, $\overline{Q}$)	t _{pLH} t _{pHL}		2.0	—	67	160	—	200		
			4.5	—	20	32	—	40		
			6.0	—	16	27	—	34		
Output Pulse Width	tw _{OUT}	Cx = 28pF Rx = 6KΩ (V _{CC} = 2V) Rx = 2KΩ (V _{CC} = 4.5V,6V)	2.0	—	700	2000	—	2500	ns	
			4.5	—	250	400	—	500		
			6.0	—	210	340	—	425		
			Cx = 0.01μF Rx = 10KΩ	2.0	90	110	130	90	130	μs
				4.5	95	105	115	95	115	
				6.0	95	105	115	95	115	
			Cx = 0.1μF Rx = 10KΩ	2.0	0.9	1.0	1.2	0.9	1.2	ms
				4.5	0.9	1.0	1.1	0.9	1.1	
				6.0	0.9	1.0	1.1	0.9	1.1	
Output Pulse Width Error Between Circuits (In same Package)	Δtw _{OUT}			—	± 1	—	—	—	%	
Input Capacitance	C _{IN}			—	5	10	—	10	pF	
Power Dissipation Capacitance	C _{PD} (1)			—	174	—	—	—		

Note (1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

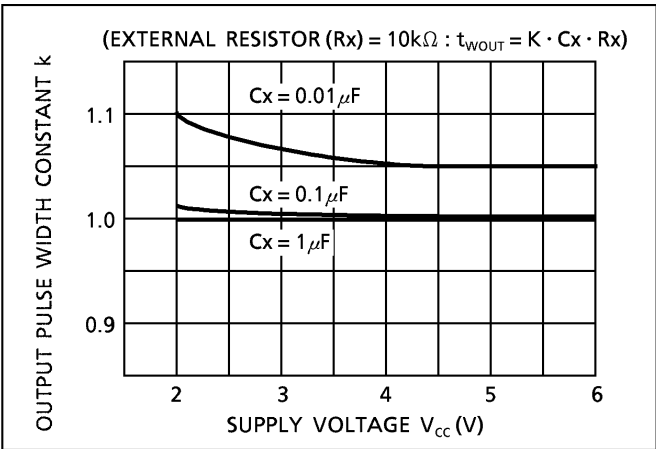
Average operating current can be obtained by the equation :

$$I_{CC}(\text{opr}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}' \cdot \text{Duty} / 100 + I_{CC} / 2 \text{ (per circuit)}$$

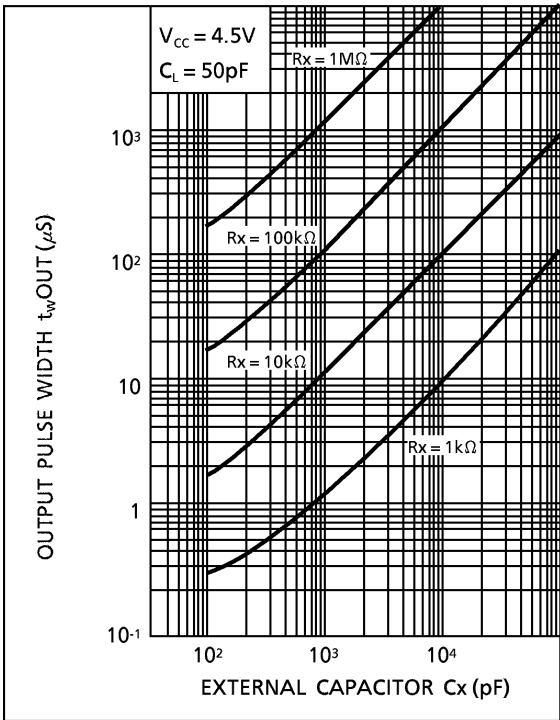
(I_{CC}' : Active Supply Current)

(Duty : %)

OUTPUT PULSE WIDTH CONSTANT K- SUPPLY VOLTAGE (TYPICAL)

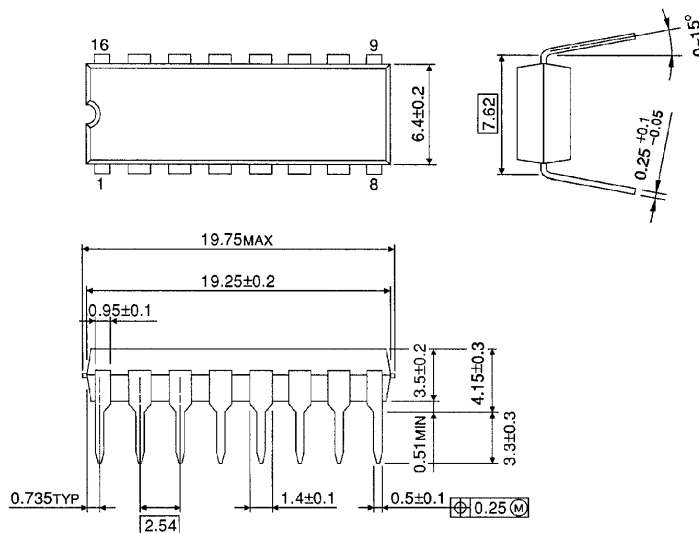


t_{WOUT} - Cx CHARACTERISTICS (TYP.)



DIP 16PIN PACKAGE DIMENSIONS (DIP16-P-300-2.54A)

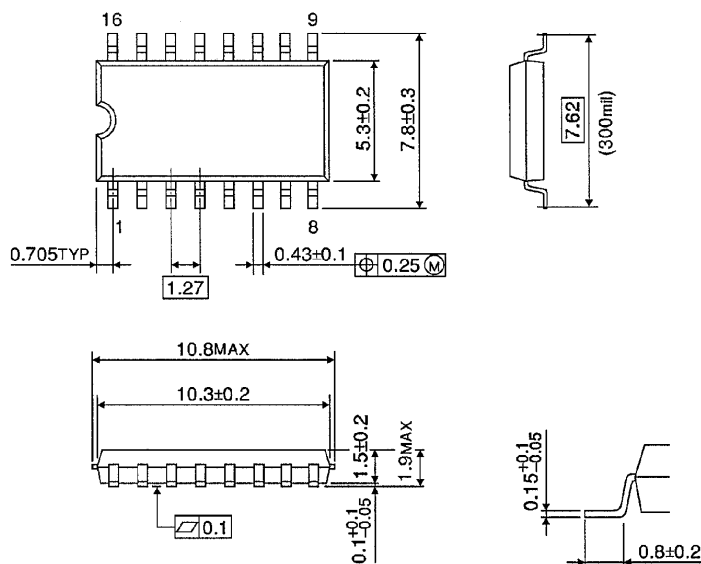
Unit in mm



Weight : 1.00g (Typ.)

SOP 16PIN (200mil BODY) PACKAGE DIMENSIONS (SOP16-P-300-1.27)

Unit in mm

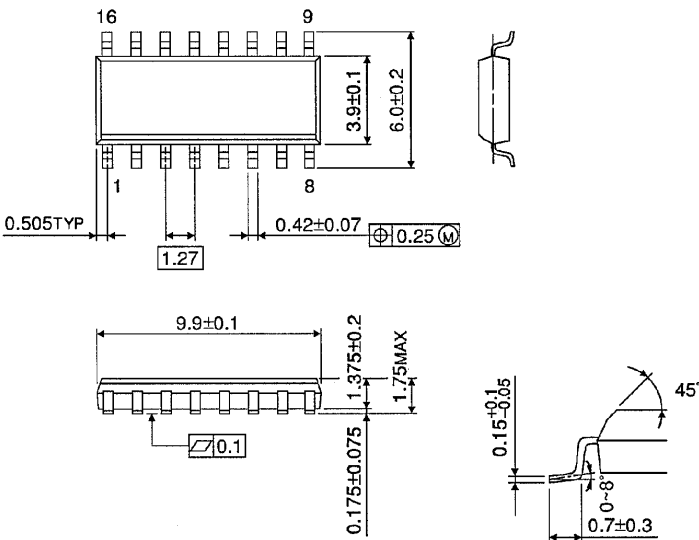


Weight : 0.18g (Typ.)

SOP 16PIN (150mil BODY) PACKAGE DIMENSIONS (SOL16-P-150 -1.27)

Unit in mm

(Note) This package is not available in Japan.



Weight : 0.13g (Typ.)

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000707EBA

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